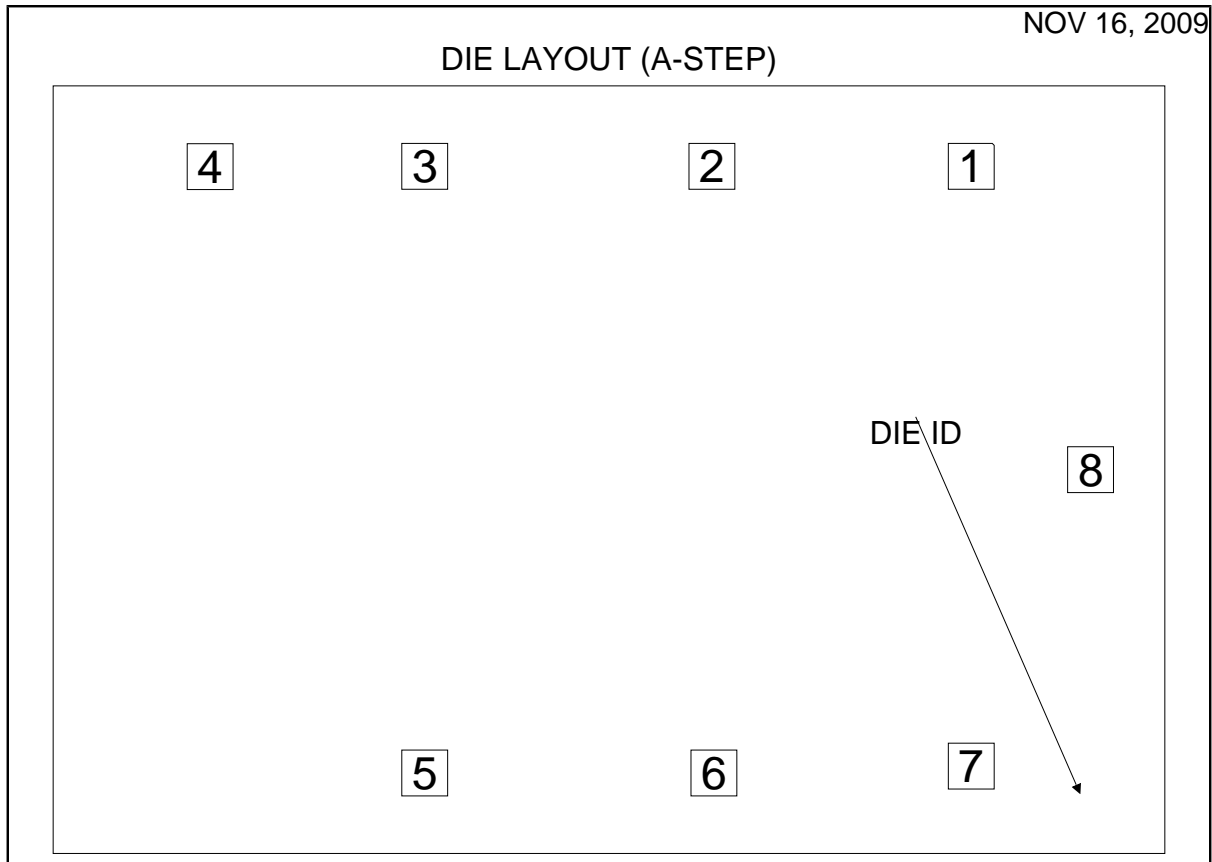


LMP2012 MDR MCD3090A  
Dual, High Precision, Rail-to-Rail Output Operational Amplifier



**DIE/WAFER CHARACTERISTICS**

| Fabrication Attributes      |  | General Die Information     |                   |
|-----------------------------|--|-----------------------------|-------------------|
| Physical Die Identification | LMV2012A                                     | Bond Pad Opening Size (min) | 88.00µm x 88.00µm |
| Die Step                    | A  | Bond Pad Metalization       | AL1.0%SI0.5%CU    |
| Physical Attributes         |  | Passivation                 | PECVDOX NITRIDE   |
| Wafer Diameter              | 150mm  | Back Side Metal             | Bare Back         |
| Die Size (Drawn)            | 2133.60µm x 1473.20µm<br>84.0mils x 58.0mils | Back Side Connection        | Floating or GND   |
| Thickness                   | 304.8µm Nominal                              |                             |                   |
| Min Pitch                   | 493.92µm                                     |                             |                   |

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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| Die Bond Pad Coordinate Locations(A-Step)   |            |                 |      |          |   |    |
|---|------------|-----------------|------|----------|---|----|
| (Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection, N.U. = Not Used |            |                 |      |          |   |    |
| Signal Name   | Pad Number | X/Y Coordinates |      | Pad Size |   |    |
|   |            | X               | Y    | X        | Y |    |
|   | 1          | 695             | 582  | 88       | x | 88 |
|   | 2          | 198             | 582  | 88       | x | 88 |
|   | 3          | -354            | 582  | 88       | x | 88 |
|   | 4          | -766            | 582  | 88       | x | 88 |
|   | 5          | -354            | -582 | 88       | x | 88 |
|   | 6          | 201             | -582 | 88       | x | 88 |
|   | 7          | 695             | -569 | 88       | x | 88 |
|   | 8          | 924             | 0    | 88       | x | 88 |

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**Notes**

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|                               |  |
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